TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ($L^2-\pi$ -MOSV)

2SK2399

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• 4 V gate drive

• Low drain–source ON resistance : $RDS (ON) = 0.17 \Omega (typ.)$ • High forward transfer admittance : $|Y_{fs}| = 4.5 S (typ.)$ • Low leakage current : $IDSS = 100 \mu A (max) (VDS = 100 V)$

• Enhancement-mode : $V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	100	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	100	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC (Note 1)	I _D	5	Α	
	Pulse (Note 1)	I _{DP}	20	Α	
Drain power dissipation (Tc = 25°C)		P _D	20	W	
Single pulse avalanche energy (Note 2)		E _{AS}	180	mJ	
Avalanche current		I _{AR}	5	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	2	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	6.25	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	125	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

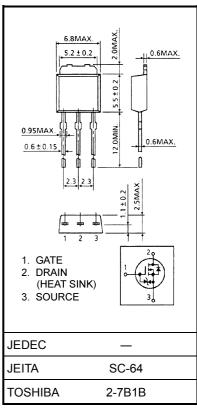
Note 2: V_{DD} = 25 V, T_{ch} = 25 °C (initial), L = 11.6 mH, R_G = 25 Ω , I_{AR} = 5 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

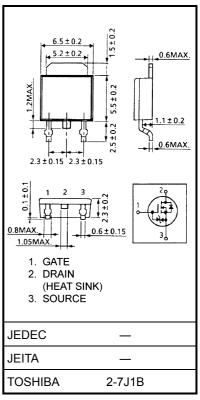
This transistor is an electrostatic sensitive device.

Please handle with caution.

Unit: mm



Weight: 0.36 g (typ.)



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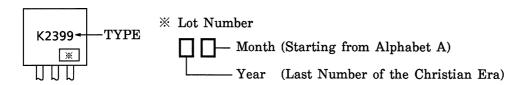
Electrical Characteristics (Ta = 25°C)

Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source br	eakdown	V _{(BR) DSS}	I _D = 10 mA, V _{GS} = 0 V	100	_	_	٧
Gate threshold v	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	_	2.0	V
.	-	V _{GS} = 4 V, I _D = 2.5 A	_	0.22	0.30	Ω	
Drain-source ON resistance		R _{DS (ON)}	V _{GS} = 10 V, I _D = 2.5 A	_	0.17		
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 2.5 A	2.0	4.5	_	S
Input capacitano	е	C _{iss}		_	500	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	80	_	pF
Output capacitance		C _{oss}	1		190	_	
Switching time	Rise time	t _r	V _{GS} _{ov} I _D =2.5A ov _{OUT}	_	17	_	
	Turn-on time	t _{on}	$\begin{array}{c c} & & & & \\ & &$	_	25		ns
	Fall time	t _f	<i>m m</i> 6	_	50		113
	Turn-off time	t _{off}	$V_{DD} = 50V$ Duty $\leq 1\%$, $t_w = 10 \mu s$	_	195	_	
Total gate charge (Gate-source plus gate-drain)		Qg			22	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx 80 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		15	_	nC
Gate-drain ("miller") charge		Q _{gd}		_	7	_	

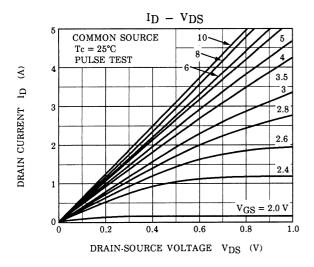
Source-Drain Ratings and Characteristics (Ta = 25°C)

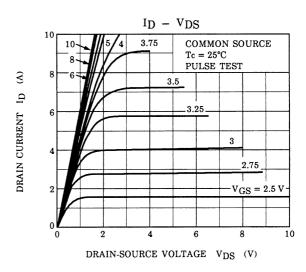
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	-	_	5	Α
Pulse drain reverse current (Note 1)	I _{DRP}	-	_	_	20	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 5 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 5 A, V _{GS} = 0 V, dI _{DR} / dt = 50 A / μs	-	160	_	ns
Reverse recovery charge	Q _{rr}		_	0.28	_	μC

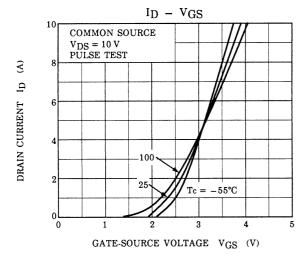
Marking

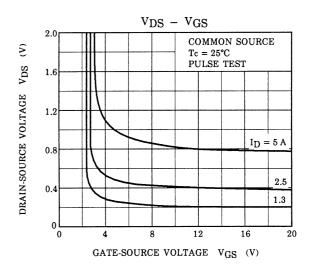


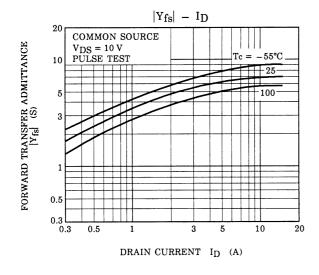
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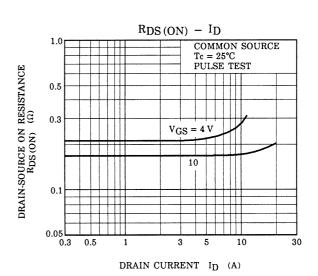




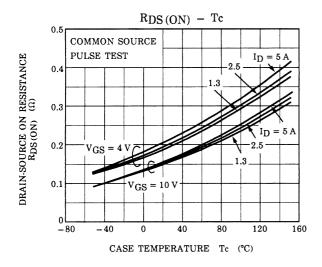


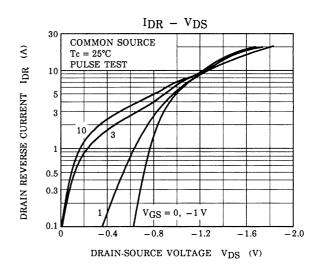


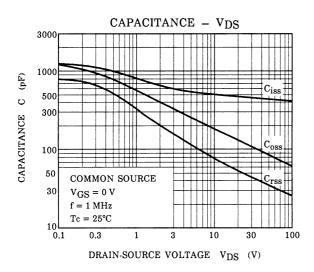


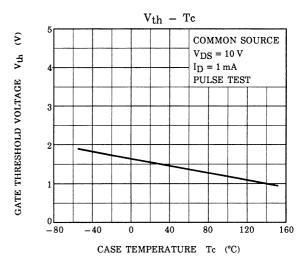


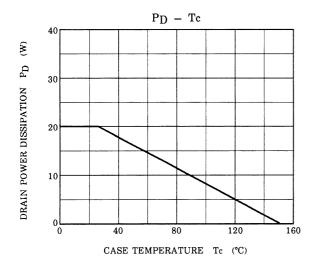
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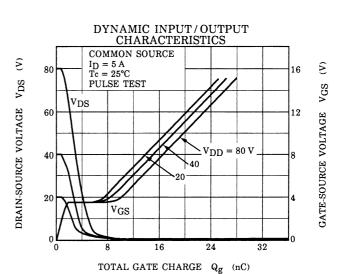




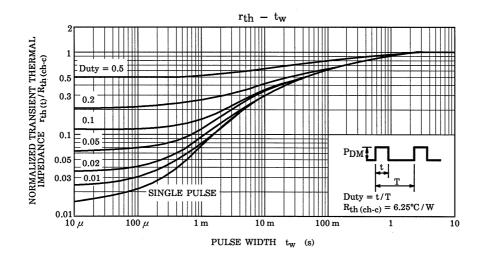


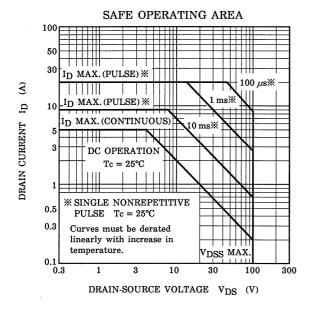


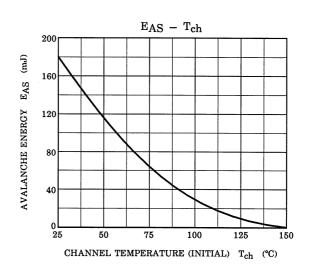


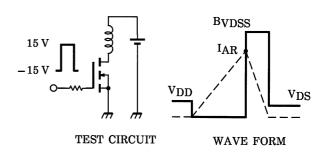


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$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 25~V,~L = 11.6~mH \end{aligned} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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